

U RESIN Tile Adhesive



U RESIN Tile Adhesive can be used to bond a wide range of materials to themselves and other materials. Typical applications include the bonding of wear plates and alumina ceramic tiles in mineral processing equipment to metal and fibre glass structures.

It can also be used as repair putty/gap filler in non critical applications.

PROFILE:

	PART A	PART B	MIXED
Colour	OFF WHITE	WHITE	WHITE
Mix Ration (by Weight)	2	1	
Pot Life @ 25°C (mins)			30
Thin Film Gel Time			2hrs
Tensile Strength			25MPa
Specific Gravity	1.65	1.55	1.61
Coverage per M2 @ 1mm			1.7kg
Flexural Strength			15MPa
Tensile Bond Strength			12MPa
Ultimate Compressive Strength			80MPa

U RESIN Tile Adhesive is a two pack, 100% solids epoxy which has a paste like consistency when mixed. This enables parts to be bonded with minimum clamping. Parts to be bonded should be suitably prepared e.g. by abrading and/or solvent cleaning.

The two adhesive components should be placed on a mixing board and mixed using a spatula or trowel until a uniform white colour is obtained.

The mixed adhesive is now applied to the prepared surfaces using a notched trowel or spatula. The two surfaces are now matted together with clamping if required ensuring that excess materials flows from the bond line.

The assembly is allowed to cure for at least 24 hours at 25°C.

FEATURES

- Bonds a wide range of materials
- Easy application
- Fast cure time

The information contained herein is true and accurate, based on laboratory conditions. It is recommended that the user contact the manufacturer to confirm suitability as field conditions may vary and yield different results. Testing of this product is strongly recommended to confirm suitability for specific applications. Data should not be used for specification purposes.